

EXHIBIT I

Bryan Staker

Glimmer Glass Networks

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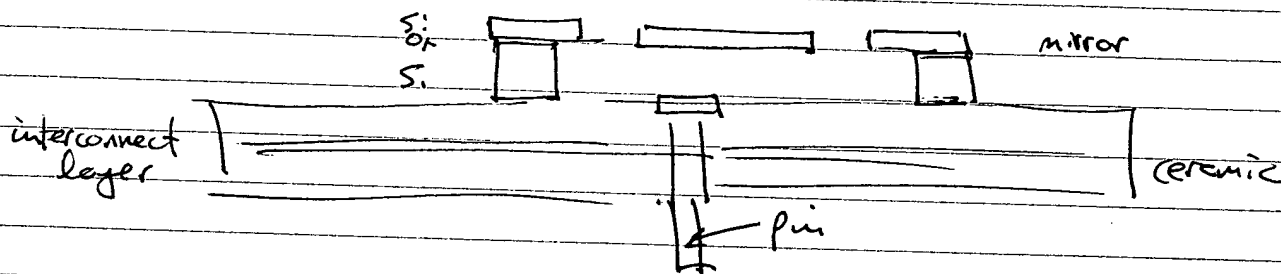
Notebook #1

Patent Disclosure

9/6/00

"Bonding of MEMS to Ceramic Substrate"

Idea: Create MEMS mirrors on an SOI wafer ~~and bond to a ceramic substrate~~ and bond to a ceramic substrate. Bonding can be done w/ an adhesive.



Advantages

1. No wafer bonding required of SOI wafer
2. Interconnect technology is well known
3. Tolerances can be fairly loose

Disadvantage

1. Thermal CTE mismatch
- possible solution:
- A. Bond several smaller pieces of silicon
 - B. Use "expandable" epoxy

Invented jointly by Eric Bogachin & Bryan Staker on Aug 23, 2000

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9/6/00

Witnessed and understood by Bill Banyard

WB 9/6/00